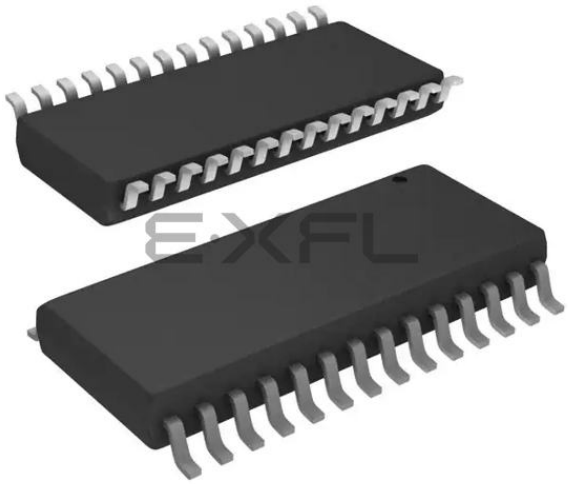
Microchip Technology - DSPIC33EP256GP502-I/SO Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256gp502-i-so

TABLE 4-16: QEI1 REGISTER MAP FOR dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
QEI1CON	01C0	QEIEN	—	QEISIDL	PIMOD<2:0>			IMV<1:0>		—	INTDIV<2:0>			CNTPOL	GATEN	CCM<1:0>		0000
QEI1IOC	01C2	QCAPEN	FLTREN	QFDIV<2:0>			OUTFNC<1:0>		SWPAB	HOMPOL	IDXPOL	QEBPOL	QEAPOL	HOME	INDEX	QEB	QEA	000x
QEI1STAT	01C4	—	—	PCHEQIRQ	PCHEQIEN	PCLEQIRQ	PCLEQIEN	POSOVIRQ	POSOVIEN	PCIIRQ	PCIIEN	VELOVIRQ	VELOVIEN	HOMIRQ	HOMIEN	IDXIRQ	IDXIEN	0000
POS1CNTL	01C6	POSCNT<15:0>																0000
POS1CNTH	01C8	POSCNT<31:16>																0000
POS1HLD	01CA	POSHLD<15:0>																0000
VEL1CNT	01CC	VELCNT<15:0>																0000
INT1TMRL	01CE	INTTMR<15:0>																0000
INT1TMRH	01D0	INTTMR<31:16>																0000
INT1HLDL	01D2	INTHLD<15:0>																0000
INT1HLDH	01D4	INTHLD<31:16>																0000
INDX1CNTL	01D6	INDXCNT<15:0>																0000
INDX1CNTH	01D8	INDXCNT<31:16>																0000
INDX1HLD	01DA	INDXHLD<15:0>																0000
QEI1GECL	01DC	QEIGEC<15:0>																0000
QEI1ICL	01DC	QEIIC<15:0>																0000
QEI1GECH	01DE	QEIGEC<31:16>																0000
QEI1ICH	01DE	QEIIC<31:16>																0000
QEI1LECL	01E0	QEILEC<15:0>																0000
QEI1LECH	01E2	QEILEC<31:16>																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 10-1: PMD1: PERIPHERAL MODULE DISABLE CONTROL REGISTER 1 (CONTINUED)

bit 3 **SPI1MD:** SPI1 Module Disable bit
1 = SPI1 module is disabled
0 = SPI1 module is enabled

bit 2 **Unimplemented:** Read as '0'

bit 1 **C1MD:** ECAN1 Module Disable bit(2)
1 = ECAN1 module is disabled
0 = ECAN1 module is enabled

bit 0 **AD1MD:** ADC1 Module Disable bit
1 = ADC1 module is disabled
0 = ADC1 module is enabled

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
2: This bit is available on dsPIC33EPXXXGP50X and dsPIC33EPXXXMC50X devices only.

REGISTER 11-8: RPINR14: PERIPHERAL PIN SELECT INPUT REGISTER 14 (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEB1R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEA1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **QEB1R<6:0>:** Assign B (QEB) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as ‘0’

bit 6-0 **QEA1R<6:0>:** Assign A (QEA) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

REGISTER 15-2: OCxCON2: OUTPUT COMPARE x CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0
FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32
bit 15							bit 8

R/W-0	R/W-0, HS	R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0
OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **FLTMD:** Fault Mode Select bit
1 = Fault mode is maintained until the Fault source is removed; the corresponding OCFLTx bit is cleared in software and a new PWM period starts
0 = Fault mode is maintained until the Fault source is removed and a new PWM period starts

bit 14 **FLTOUT:** Fault Out bit
1 = PWM output is driven high on a Fault
0 = PWM output is driven low on a Fault

bit 13 **FLTTRIEN:** Fault Output State Select bit
1 = OCx pin is tri-stated on a Fault condition
0 = OCx pin I/O state is defined by the FLTOUT bit on a Fault condition

bit 12 **OCINV:** Output Compare x Invert bit
1 = OCx output is inverted
0 = OCx output is not inverted

bit 11-9 **Unimplemented:** Read as '0'

bit 8 **OC32:** Cascade Two OCx Modules Enable bit (32-bit operation)
1 = Cascade module operation is enabled
0 = Cascade module operation is disabled

bit 7 **OCTRIG:** Output Compare x Trigger/Sync Select bit
1 = Triggers OCx from the source designated by the SYNCSELx bits
0 = Synchronizes OCx with the source designated by the SYNCSELx bits

bit 6 **TRIGSTAT:** Timer Trigger Status bit
1 = Timer source has been triggered and is running
0 = Timer source has not been triggered and is being held clear

bit 5 **OCTRIS:** Output Compare x Output Pin Direction Select bit
1 = OCx is tri-stated
0 = Output Compare x module drives the OCx pin

Note 1: Do not use the OCx module as its own Synchronization or Trigger source.

2: When the OCy module is turned OFF, it sends a trigger out signal. If the OCx module uses the OCy module as a Trigger source, the OCy module must be unselected as a Trigger source prior to disabling it.

3: Each Output Compare x module (OCx) has one PTG Trigger/Synchronization source. See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for more information.
PTGO0 = OC1
PTGO1 = OC2
PTGO2 = OC3
PTGO3 = OC4

REGISTER 16-15: FCLCONx: PWMx FAULT CURRENT-LIMIT CONTROL REGISTER(1)

bit 7-3 **FLTSRC<4:0>:** Fault Control Signal Source Select for PWM Generator # bits
11111 = Fault 32 **(default)**
11110 = Reserved
•
•
•
01100 = Reserved
01011 = Comparator 4
01010 = Op Amp/Comparator 3
01001 = Op Amp/Comparator 2
01000 = Op Amp/Comparator 1
00111 = Reserved
00110 = Reserved
00101 = Reserved
00100 = Reserved
00011 = Fault 4
00010 = Fault 3
00001 = Fault 2
00000 = Fault 1

bit 2 **FLTPOL:** Fault Polarity for PWM Generator # bit(2)
1 = The selected Fault source is active-low
0 = The selected Fault source is active-high

bit 1-0 **FLTMOD<1:0>:** Fault Mode for PWM Generator # bits
11 = Fault input is disabled
10 = Reserved
01 = The selected Fault source forces PWMxH, PWMxL pins to FLTDAT values (cycle)
00 = The selected Fault source forces PWMxH, PWMxL pins to FLTDAT values (latched condition)

Note 1: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a '1', the IOCONx register can only be written after the unlock sequence has been executed.

2: These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.

REGISTER 18-2: SPIxCON1: SPIx CONTROL REGISTER 1

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SSEN(2)	CKP	MSTEN	SPRE2(3)	SPRE1(3)	SPRE0(3)	PPRE1(3)	PPRE0(3)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **DISSCK:** Disable SCKx Pin bit (SPIx Master modes only)
1 = Internal SPIx clock is disabled, pin functions as I/O
0 = Internal SPIx clock is enabled

bit 11 **DISSDO:** Disable SDOx Pin bit
1 = SDOx pin is not used by the module; pin functions as I/O
0 = SDOx pin is controlled by the module

bit 10 **MODE16:** Word/Byte Communication Select bit
1 = Communication is word-wide (16 bits)
0 = Communication is byte-wide (8 bits)

bit 9 **SMP:** SPIx Data Input Sample Phase bit
Master mode:
1 = Input data is sampled at end of data output time
0 = Input data is sampled at middle of data output time
Slave mode:
SMP must be cleared when SPIx is used in Slave mode.

bit 8 **CKE:** SPIx Clock Edge Select bit(1)
1 = Serial output data changes on transition from active clock state to Idle clock state (refer to bit 6)
0 = Serial output data changes on transition from Idle clock state to active clock state (refer to bit 6)

bit 7 **SSEN:** Slave Select Enable bit (Slave mode)(2)
1 = $\overline{SSx}$ pin is used for Slave mode
0 = $\overline{SSx}$ pin is not used by the module; pin is controlled by port function

bit 6 **CKP:** Clock Polarity Select bit
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit
1 = Master mode
0 = Slave mode

Note 1: The CKE bit is not used in Framed SPI modes. Program this bit to '0' for Framed SPI modes (FRMEN = 1).
2: This bit must be cleared when FRMEN = 1.
3: Do not set both primary and secondary prescalers to the value of 1:1.

NOTES:

REGISTER 23-2: AD1CON2: ADC1 CONTROL REGISTER 2 (CONTINUED)

bit 1 **BUFM:** Buffer Fill Mode Select bit

1 = Starts the buffer filling the first half of the buffer on the first interrupt and the second half of the buffer on next interrupt

0 = Always starts filling the buffer from the start address.

bit 0 **ALTS:** Alternate Input Sample Mode Select bit

1 = Uses channel input selects for Sample MUXA on first sample and Sample MUXB on next sample

0 = Always uses channel input selects for Sample MUXA

REGISTER 23-7: AD1CSSH: ADC1 INPUT SCAN SELECT REGISTER HIGH(1)

R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
CSS31	CSS30	—	—	—	CSS26(2)	CSS25(2)	CSS24(2)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CSS31:** ADC1 Input Scan Selection bit
1 = Selects CTMU capacitive and time measurement for input scan (Open)
0 = Skips CTMU capacitive and time measurement for input scan (Open)

bit 14 **CSS30:** ADC1 Input Scan Selection bit
1 = Selects CTMU on-chip temperature measurement for input scan (CTMU TEMP)
0 = Skips CTMU on-chip temperature measurement for input scan (CTMU TEMP)

bit 13-11 **Unimplemented:** Read as '0'

bit 10 **CSS26:** ADC1 Input Scan Selection bit(2)
1 = Selects OA3/AN6 for input scan
0 = Skips OA3/AN6 for input scan

bit 9 **CSS25:** ADC1 Input Scan Selection bit(2)
1 = Selects OA2/AN0 for input scan
0 = Skips OA2/AN0 for input scan

bit 8 **CSS24:** ADC1 Input Scan Selection bit(2)
1 = Selects OA1/AN3 for input scan
0 = Skips OA1/AN3 for input scan

bit 7-0 **Unimplemented:** Read as '0'

Note 1: All AD1CSSH bits can be selected by user software. However, inputs selected for scan, without a corresponding input on the device, convert VREFL.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

TABLE 24-1: PTG STEP COMMAND FORMAT (CONTINUED)

bit 3-0	Step Command	OPTION<3:0>	Option Description
	PTGWHI(1) or PTGWLO(1)	0000	PWM Special Event Trigger.(3)
		0001	PWM master time base synchronization output.(3)
		0010	PWM1 interrupt.(3)
		0011	PWM2 interrupt.(3)
		0100	PWM3 interrupt.(3)
		0101	Reserved.
		0110	Reserved.
		0111	OC1 Trigger event.
		1000	OC2 Trigger event.
		1001	IC1 Trigger event.
		1010	CMP1 Trigger event.
		1011	CMP2 Trigger event.
		1100	CMP3 Trigger event.
		1101	CMP4 Trigger event.
		1110	ADC conversion done interrupt.
		1111	INT2 external interrupt.
	PTGIRQ(1)	0000	Generate PTG Interrupt 0.
		0001	Generate PTG Interrupt 1.
		0010	Generate PTG Interrupt 2.
		0011	Generate PTG Interrupt 3.
		0100	Reserved.
		• • •	• • •
		1111	Reserved.
	PTGTRIG(2)	00000	PTGO0.
		00001	PTGO1.
		• • •	• • •
		11110	PTGO30.
		11111	PTGO31.

Note 1: All reserved commands or options will execute but have no effect (i.e., execute as a NOP instruction).

2: Refer to Table 24-2 for the trigger output descriptions.

3: This feature is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

Most instructions are a single word. Certain double-word instructions are designed to provide all the required information in these 48 bits. In the second word, the 8 MSbs are '0's. If this second word is executed as an instruction (by itself), it executes as a NOP.

The double-word instructions execute in two instruction cycles.

Most single-word instructions are executed in a single instruction cycle, unless a conditional test is true, or the Program Counter is changed as a result of the instruction, or a PSV or Table Read is performed, or an SFR register is read. In these cases, the execution takes multiple instruction cycles with the additional instruction cycle(s) executed as a NOP. Certain instructions that involve skipping over the subsequent instruction require either two or three cycles if the skip is performed, depending on whether the instruction being skipped is a single-word or two-word instruction. Moreover, double-word moves require two cycles.

Note: For more details on the instruction set, refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157).

For more information on instructions that take more than one instruction cycle to execute, refer to **"CPU"** (DS70359) in the *"dsPIC33/PIC24 Family Reference Manual"*, particularly the **"Instruction Flow Types"** section.

TABLE 28-1: SYMBOLS USED IN OPCODE DESCRIPTIONS

Field	Description
#text	Means literal defined by "text"
(text)	Means "content of text"
[text]	Means "the location addressed by text"
{ }	Optional field or operation
a ∈ {b, c, d}	a is selected from the set of values b, c, d
<n:m>	Register bit field
.b	Byte mode selection
.d	Double-Word mode selection
.S	Shadow register select
.w	Word mode selection (default)
Acc	One of two accumulators {A, B}
AWB	Accumulator write back destination address register ∈ {W13, [W13]+ = 2}
bit4	4-bit bit selection field (used in word addressed instructions) ∈ {0...15}
C, DC, N, OV, Z	MCU Status bits: Carry, Digit Carry, Negative, Overflow, Sticky Zero
Expr	Absolute address, label or expression (resolved by the linker)
f	File register address ∈ {0x0000...0x1FFF}
lit1	1-bit unsigned literal ∈ {0,1}
lit4	4-bit unsigned literal ∈ {0...15}
lit5	5-bit unsigned literal ∈ {0...31}
lit8	8-bit unsigned literal ∈ {0...255}
lit10	10-bit unsigned literal ∈ {0...255} for Byte mode, {0:1023} for Word mode
lit14	14-bit unsigned literal ∈ {0...16384}
lit16	16-bit unsigned literal ∈ {0...65535}
lit23	23-bit unsigned literal ∈ {0...8388608}; LSb must be '0'
None	Field does not require an entry, can be blank
OA, OB, SA, SB	DSP Status bits: ACCA Overflow, ACCB Overflow, ACCA Saturate, ACCB Saturate
PC	Program Counter
Slit10	10-bit signed literal ∈ {-512...511}
Slit16	16-bit signed literal ∈ {-32768...32767}
Slit6	6-bit signed literal ∈ {-16...16}
Wb	Base W register ∈ {W0...W15}
Wd	Destination W register ∈ { Wd, [Wd], [Wd++], [Wd--], [++Wd], [--Wd] }
Wdo	Destination W register ∈ { Wnd, [Wnd], [Wnd++], [Wnd--], [++Wnd], [--Wnd], [Wnd+Wb] }

TABLE 30-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**		
Operating Current (IDD)(1)						
DC20d	9	15	mA	-40°C	3.3V	10 MIPS
DC20a	9	15	mA	+25°C		
DC20b	9	15	mA	+85°C		
DC20c	9	15	mA	+125°C		
DC22d	16	25	mA	-40°C	3.3V	20 MIPS
DC22a	16	25	mA	+25°C		
DC22b	16	25	mA	+85°C		
DC22c	16	25	mA	+125°C		
DC24d	27	40	mA	-40°C	3.3V	40 MIPS
DC24a	27	40	mA	+25°C		
DC24b	27	40	mA	+85°C		
DC24c	27	40	mA	+125°C		
DC25d	36	55	mA	-40°C	3.3V	60 MIPS
DC25a	36	55	mA	+25°C		
DC25b	36	55	mA	+85°C		
DC25c	36	55	mA	+125°C		
DC26d	41	60	mA	-40°C	3.3V	70 MIPS
DC26a	41	60	mA	+25°C		
DC26b	41	60	mA	+85°C		

Note 1: IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:

- Oscillator is configured in EC mode with PLL, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1){NOP();}` statement
- JTAG is disabled

FIGURE 30-9: HIGH-SPEED PWMx MODULE FAULT TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

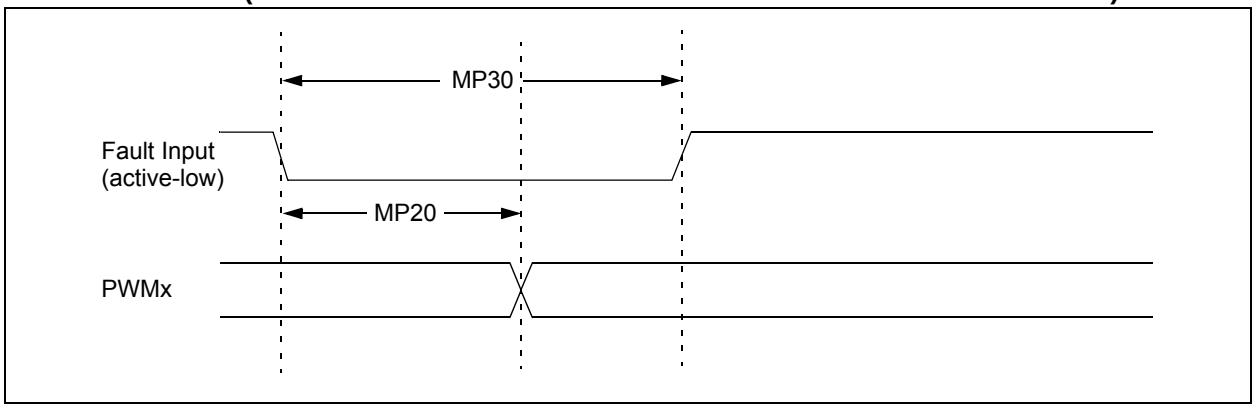
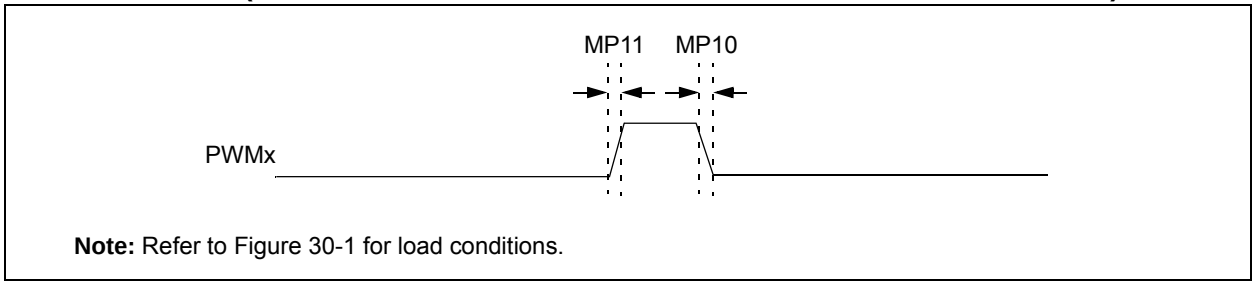


FIGURE 30-10: HIGH-SPEED PWMx MODULE TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)



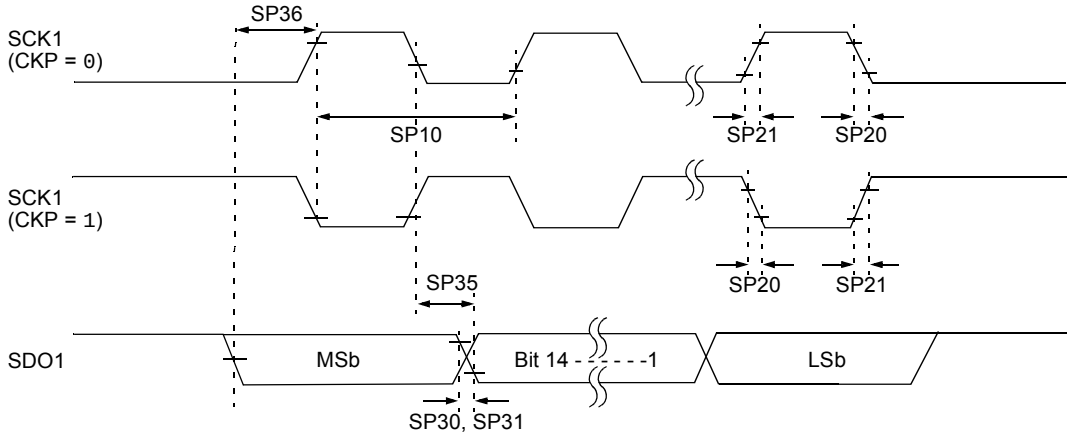
Note: Refer to Figure 30-1 for load conditions.

TABLE 30-29: HIGH-SPEED PWMx MODULE TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
MP10	TFPWM	PWMx Output Fall Time	—	—	—	ns	See Parameter DO32
MP11	TRPWM	PWMx Output Rise Time	—	—	—	ns	See Parameter DO31
MP20	TFD	Fault Input ↓ to PWMx I/O Change	—	—	15	ns	
MP30	TFH	Fault Input Pulse Width	15	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-23: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-42: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK1 Frequency	—	—	15	MHz	**(Note 3)**
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	

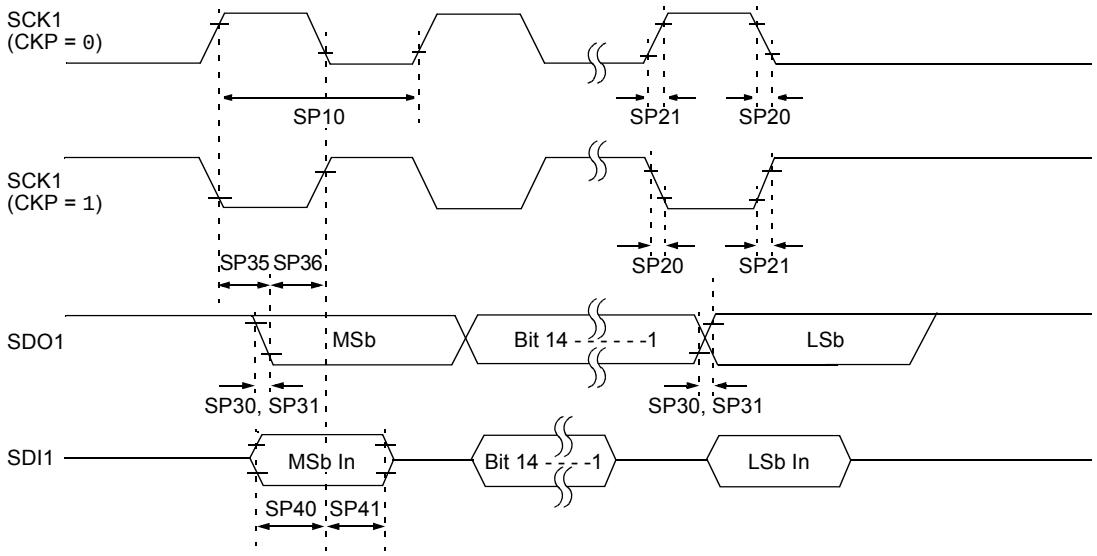
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

FIGURE 30-25: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-44: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK1 Frequency	—	—	10	MHz	-40ºC to +125ºC **(Note 3)**
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	

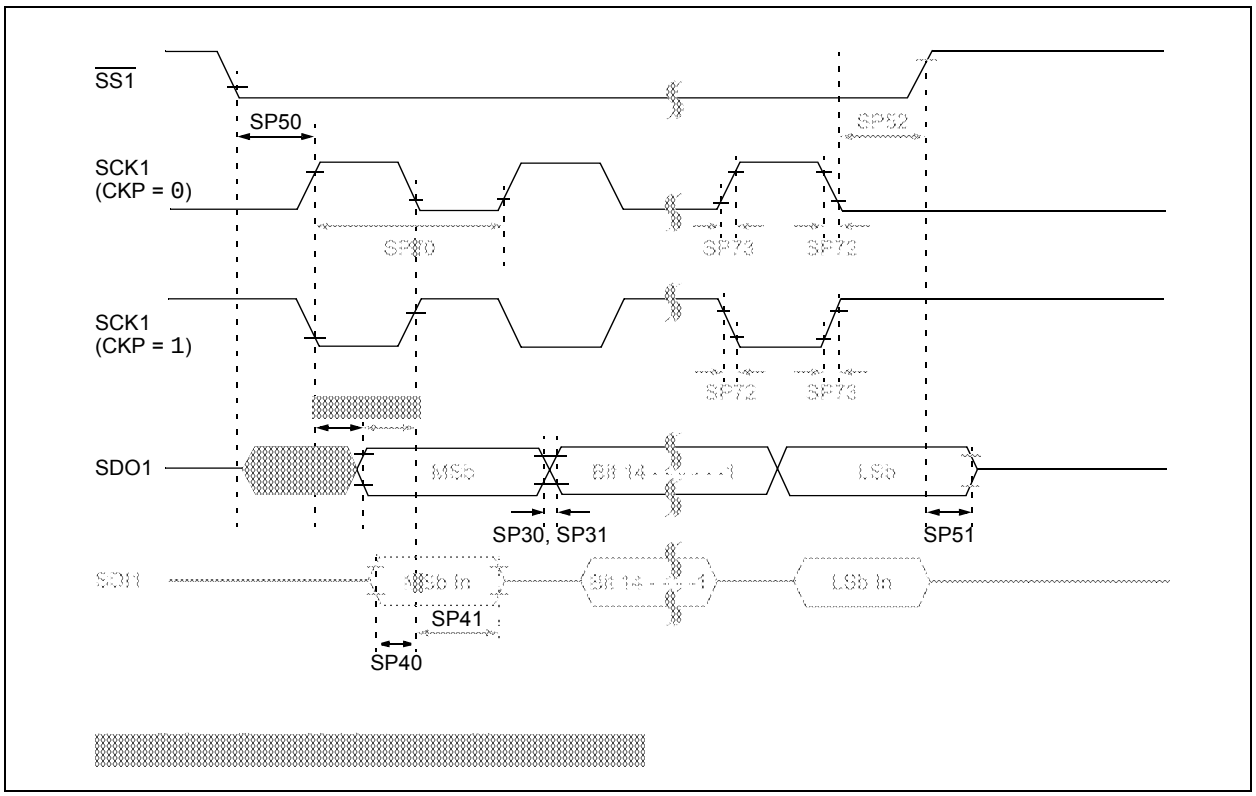
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 100 ns. The clock generated in Master mode must not violate this specification.

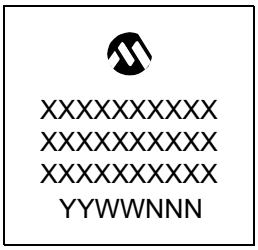
4: Assumes 50 pF load on all SPI1 pins.

FIGURE 30-29: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS



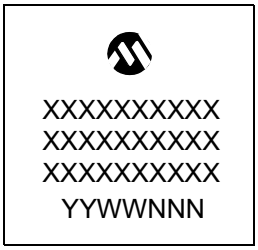
33.1 Package Marking Information (Continued)

36-Lead VTLA (TLA)



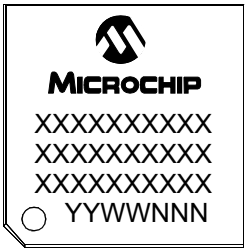
Example

44-Lead VTLA (TLA)



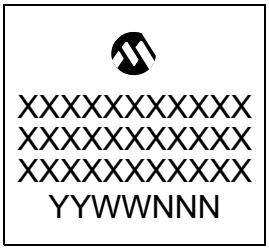
Example

44-Lead TQFP



Example

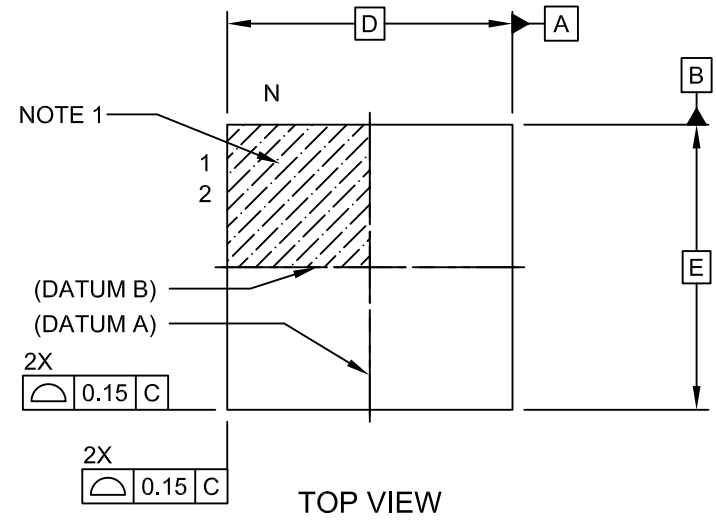
44-Lead QFN (8x8x0.9 mm)



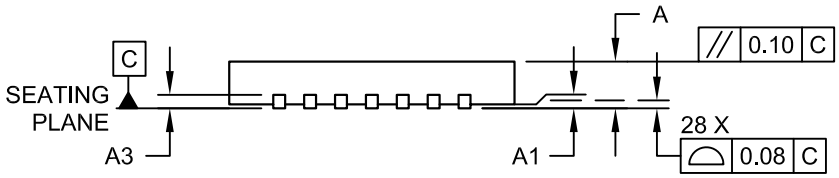
Example

28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S] With 0.40 mm Terminal Length

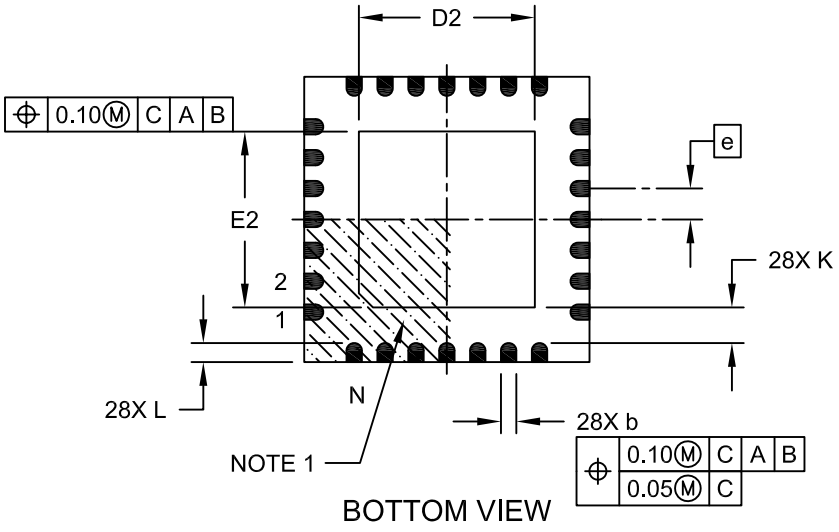
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



BOTTOM VIEW

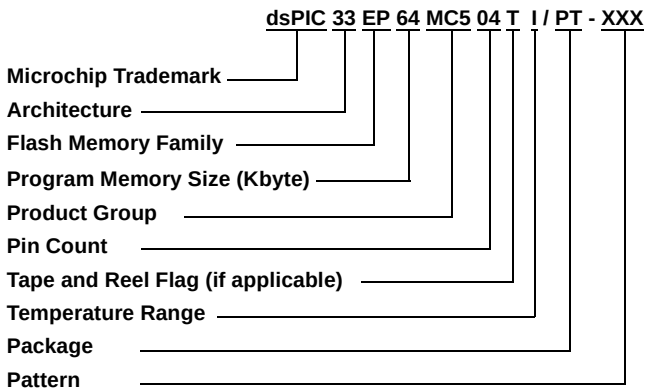
Microchip Technology Drawing C04-124C Sheet 1 of 2

TABLE A-5: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	• Throughout: qualifies all footnotes relating to the operation of analog modules below VDDMIN (replaces "will have" with "may have") • Throughout: changes all references of SPI timing parameter symbol "TscP" to "FscP" • Table 30-1: changes VDD range to 3.0V to 3.6V • Table 30-4: removes Parameter DC12 (RAM Retention Voltage) • Table 30-7: updates Maximum values at 10 and 20 MIPS • Table 30-8: adds Maximum IPD values, and removes all ΔIWDT entries • Adds new Table 30-9 (Watchdog Timer Delta Current) with consolidated values removed from Table 30-8. All subsequent tables are renumbered accordingly. • Table 30-10: adds footnote for all parameters for 1:2 Doze ratio • Table 30-11: - changes Minimum and Maximum values for D120 and D130 - adds Minimum and Maximum values for D131 - adds Minimum and Maximum values for D150 through D156, and removes Typical values • Table 30-12: - reformats table for readability - changes IOL conditions for DO10 • Table 30-14: adds footnote to D135 • Table 30-17: changes Minimum and Maximum values for OS30 • Table 30-19: - splits temperature range and adds new values for F20a - reduces temperature range for F20b to extended temperatures only • Table 30-20: - splits temperature range and adds new values for F21a - reduces temperature range for F20b to extended temperatures only • Table 30-53: - adds Maximum value to CM30 - adds footnote ("Parameter characterized...") to multiple parameters • Table 30-55: adds Minimum and Maximum values for all CTMUI specifications, and removes Typical values • Table 30-57: adds new footnote to AD09 • Table 30-58: - removes all specifications for accuracy with external voltage references - removes Typical values for AD23a and AD24a - replaces Minimum and Maximum values for AD21a, AD22a, AD23a and AD24a with new values, split by Industrial and Extended temperatures - removes Maximum value of AD30 - removes Minimum values from AD31a and AD32a - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-59: - removes all specifications for accuracy with external voltage references - removes Maximum value of AD30 - removes Typical values for AD23b and AD24b - replaces Minimum and Maximum values for AD21b, AD22b, AD23b and AD24b with new values, split by Industrial and Extended temperatures - removes Minimum and Maximum values from AD31b, AD32b, AD33b and AD34b - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-61: Adds footnote to AD51
Section 32.0 "DC and AC Device Characteristics Graphs"	• Updates Figure 32-6 (Typical IDD @ 3.3V) with individual current vs. processor speed curves for the different program memory sizes
Section 33.0 "Packaging Information"	• Replaces drawing C04-149C (64-pin QFN, 7.15 x 7.15 exposed pad) with C04-154A (64-pin QFN, 5.4 x 5.4 exposed pad)

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Examples:

dsPIC33EP64MC504-I/PT:
dsPIC33, Enhanced Performance,
64-Kbyte Program Memory,
Motor Control, 44-Pin,
Industrial Temperature,
TQFP package.

Architecture:	33	=	16-bit Digital Signal Controller
	24	=	16-bit Microcontroller
Flash Memory Family:	EP	=	Enhanced Performance
Product Group:	GP	=	General Purpose family
	MC	=	Motor Control family
Pin Count:	02	=	28-pin
	03	=	36-pin
	04	=	44-pin
	06	=	64-pin
Temperature Range:	I	=	-40°C to+85°C (Industrial)
	E	=	-40°C to+125°C (Extended)
Package:	ML	=	Plastic Quad, No Lead Package - (44-pin) 8x8 mm body (QFN)
	MM	=	Plastic Quad, No Lead Package - (28-pin) 6x6 mm body (QFN-S)
	MR	=	Plastic Quad, No Lead Package - (64-pin) 9x9 mm body (QFN)
	MV	=	Thin Quad, No Lead Package - (48-pin) 6x6 mm body (UQFN)
	PT	=	Plastic Thin Quad Flatpack - (44-pin) 10x10 mm body (TQFP)
	PT	=	Plastic Thin Quad Flatpack - (64-pin) 10x10 mm body (TQFP)
	SO	=	Plastic Small Outline, Wide - (28-pin) 7.50 mm body (SOIC)
	SP	=	Skinny Plastic Dual In-Line - (28-pin) 300 mil body (SPDIP)
	SS	=	Plastic Shrink Small Outline - (28-pin) 5.30 mm body (SSOP)
	TL	=	Very Thin Leadless Array - (36-pin) 5x5 mm body (VTLA)
	TL	=	Very Thin Leadless Array - (44-pin) 6x6 mm body (VTLA)